

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Nick Kuo</td> <td>09/10/2003</td> </tr> <tr> <td>Chiu-Ming Chou</td> <td>09/10/2003</td> </tr> <tr> <td>Chien-Kang Chou</td> <td>09/10/2003</td> </tr> <tr> <td>Chu-Fu Lin</td> <td>09/10/2003</td> </tr> </tbody> </table>		Name	Execution Date	Nick Kuo	09/10/2003	Chiu-Ming Chou	09/10/2003	Chien-Kang Chou	09/10/2003	Chu-Fu Lin	09/10/2003
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RECEIVING PARTY DATA											
<table border="1"> <tr> <td>Name:</td> <td>Megic Corporation</td> </tr> <tr> <td>Street Address:</td> <td>No. 21, R&amp;D 1st Road, Science-Based Industrial Park</td> </tr> <tr> <td>City:</td> <td>Hsinchu</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>ROC</td> </tr> </table>		Name:	Megic Corporation	Street Address:	No. 21, R&D 1st Road, Science-Based Industrial Park	City:	Hsinchu	State/Country:	TAIWAN	Postal Code:	ROC
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PROPERTY NUMBERS Total: 1											
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CORRESPONDENCE DATA											
Fax Number: 8586582502 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i> Phone: (858) 651-5205 Email: usdocketing@qualcomm.com Correspondent Name: QUALCOMM Incorporated Address Line 1: 5775 Morehouse Drive Address Line 4: San Diego, CALIFORNIA 92121-1714											
ATTORNEY DOCKET NUMBER:	092967C1C1										
NAME OF SUBMITTER:	Karen M Cruz										
Signature:	/Karen M Cruz/										

Date:

07/09/2013

Total Attachments: 2

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(48) 7394161

MEGIC-2003-004

20040323

## ASSIGNMENT

WHEREAS,

- |                    |                   |
|--------------------|-------------------|
| 1. Nick Kuo        | 2. Chiu-Ming Chou |
| 3. Chien-Kang Chou | 4. Chu-Fu Lin     |

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **CHIP STRUCTURE WITH BUMPS AND TESTING PADS**

☐ Filed: Serial No.

☒ Executed concurrently with the execution of this instrument

WHEREAS, Megic Corporation  
of No. 21, R&D 1st Rd., Science-Based Industrial Park Hsinchu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

# ASSIGNMENT CONTINUED

20040323

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Nick Kuo  
Signature:

Sept. 10, 2003  
Date:

Sole or First Joint Inventor: Nick Kuo

Chiu-Ming Chou  
Signature:

Sept. 10, 2003  
Date:

Second Joint Inventor(if any): Chiu-Ming Chou

Chien-Kang Chou  
Signature:

Sept. 10, 2003  
Date:

Third Joint Inventor(if any): Chien-Kang Chou

Chu-Fu Lin  
Signature:

Sept. 10, 2003  
Date:

Fourth Joint Inventor(if any): Chu-Fu Lin